The DS92LV16 is a member of National's robust and easy-to-use Bus LVDS serializer/deserializer (SerDes) family already popular in a wide variety of telecom, datacom, industrial, and commercial backplane/cable interconnect applications. The DS92LV16 is similar to the original 10-bit Bus LVDS SerDes products, but provides a wider, 16-bit data bus payload.

The DS92LV16 is very flexible and performs over a wide, 25 - 80 MHz frequency range. Both the transmit clock and receiver reference clock have high jitter tolerance, allowing the use of low cost clock sources. The serializer and deserializer sections are fully independent and can be operated at different frequencies. This is useful when upstream and downstream rates are not balanced. In addition, the serializer and deserializer blocks can be powered down independently if only one transmission direction is needed.

The receiver locks to random data, eliminating the need to interrupt normal traffic with PLL training patterns after hot plug events. The usual loss-of-lock feedback path from receiver to transmitter is also not required.

Line and local loopback test modes allow the designer to segregate portions of the system to facilitate system diagnostics.
The Bus LVDS SerDes architecture was developed in conjunction with major telecommunications customers who desired features not provided by common 8b/10b datacom SerDes chipsets. Instead of scrambling each byte into a new 10-bit code as with 8b/10b coding, the Bus LVDS SerDes coding scheme frames each data word with two embedded clock bits, one high and one low. These embedded clock bits create a rising edge transition which provides precise timing and framing information to the receiver on every clock cycle.

The resulting benefits of the Bus LVDS SerDes architecture include:

- Lock to random data for true hot plug capability—lock can be achieved without interrupting traffic with PLL training patterns and without a loss-of-lock feedback path from receiver to transmitter.
- The relaxed ±5% RefCLK frequency specification means the receiver does not require a precise reference clock source to recover data reliably.
- Jitter-tolerant TCLK transmit clock input eliminates the requirement to use a high-grade telecom/datacom transmit clock source and also simplifies external loopback operations.
- Non-byte-oriented bus widths such as 10-bits are available.
Bus Topologies/Applications

The DS92LV16 is designed mainly for point-to-point applications, but you may also use it for multidrop interconnects under certain circumstances.

**Point-to-Point**

The DS92LV16 can deliver the full 1.28 Gbps payload in each direction over point-to-point backplanes and cables (distance depends on cable quality, transmission speed, etc.) This performance is also possible when driving multiple receivers through a low jitter LVDS-to-LVDS switch/distribution chip in a distributed point-to-point configuration. In all point-to-point applications, you must place a termination resistor close to each receiver input.

**Multidrop**

The DS92LV16 may be used in limited multidrop (also known as point-to-multipoint) backplane applications driving a few receiver loads. The output structure is a modified Bus LVDS-type circuit that regulates the $V_{DD}$ (output differential voltage) over a narrow range of loads. The driver expects to see a 100-Ohm load, but may also operate with loads as low as 50 Ohms with reduced voltage swing. The number of receivers allowed depends upon the bandwidth of the interconnecting path, the spacing of the nodes, and also the length of the resulting stubs. The DS92LV16's fast Bus LVDS output edge rates are optimized for the high throughput of the part, thus stub length must be minimized mechanically or electrically using “stub hider” buffer devices.

See the “Backplane” section for more information.

### Typical Bus Performance

<table>
<thead>
<tr>
<th>Backplane Topology</th>
<th>Configuration</th>
<th>Performance</th>
</tr>
</thead>
<tbody>
<tr>
<td>Point-to-Point</td>
<td>1Tx · 1Rx</td>
<td>Chipset Maximum</td>
</tr>
<tr>
<td>Distributed Point-to-Point</td>
<td>1Tx · Switch · Multiple Rx</td>
<td>Chipset Maximum</td>
</tr>
<tr>
<td>Limited Multidrop</td>
<td>1Tx · 2-4Rx</td>
<td>Up to 500 - 600 Mbps</td>
</tr>
<tr>
<td>Multidrop</td>
<td>1Tx · 10-20Rx</td>
<td>Up to 300 - 400 Mbps</td>
</tr>
<tr>
<td>Multipoint</td>
<td>10-20 Transceivers</td>
<td>Up to 200 - 300 Mbps</td>
</tr>
</tbody>
</table>

**Match segment $Z_g$ & $R_T$ impedances within ±10%**

(10% mismatch = 5% reflection)

$$Z_g = \frac{\text{Backplane or Cable}}{\text{PCB}} = \frac{\text{Stub}}{\text{Length}}$$

**Minimize stub lengths**

**Use appropriate connector pin assignment & routing**

---

---
Backplanes

Point-to-Point

The DS92LV16 achieves the maximum 1.28 Gbps performance in controlled 100-Ohm differential impedance point-to-point or distributed point-to-point FR-4 backplanes, though other backplane materials such as GETEK, Rogers, or hybrids may also be employed if desired. The backplane should be designed with sufficient bandwidth to support the desired data rate. For example, for 1 Gbps (500 MHz), a media bandwidth of 1.5 GHz is typically required.

Multidrop

In some instances, the DS92LV16 may be used in multidrop backplanes driving a 2 - 4 receiver loads. Actual performance depends on the bandwidth of the interconnect. Pay close attention on minimizing stub lengths (connector plus trace) to < 2 cm. Depending on data rate, National's LVDS DS90LV001 or other future “stub hider” chips should used to reduce stub lengths seen by the signal on the backplane. Receiver loads should be widely spaced to reduce the transmission segment to stub length ratio and/or placed far away from the transmitter to allow the edge rate to be slowed by the interconnect before reaching the first stub.

Due to fast edge rates, the DS92LV16 is typically not recommended for driving more than a few multidrop loads.

Termination

Termination is required. Choose the termination resistor value $R_L$ to match the loaded differential impedance of the transmission line. In a point-to-point backplane, the termination value is typically 100 Ohms. If a smaller output signal swing is desired, the line may be terminated at both the transmitter output as well as the receiver input, reducing the effective load seen by the transmitter by half.

In a multidrop backplane, the added capacitive loading of the extra receivers lowers the differential impedance, requiring a lower value termination resistor. Again, the termination resistor(s) value chosen should match the loaded backplane impedance. Note that loads less than 50 Ohms reduce the output signal swing below ±350 mV, compromising noise margins.

The typical capacitance of the DS92LV16 serial Bus LVDS inputs and outputs is about 5 pF.
Designing with LVDS is actually quite easy if you remember that LVDS is a high speed, differential signaling technology.

**High Speed:** LVDS pairs should be considered transmission lines. Anything over a few centimeters should have controlled impedance. LVDS termination is always required.

**Differential:** Each LVDS pair should be treated as one signal. Both wires of each pair should "see" the same electrical path.

---

**General Printed Circuit Board (PCB) Recommendations**

- Use at least 4 PCB board layers (Bus LVDS signals, ground, power, and TTL signals).
- Minimize any resulting stub lengths—

  In a point-to-point bus, the resulting stub is typically the distance between the termination resistor and the receiver input pins of the DS92LV16. Place the small surface mount resistor as close to the receiver input pins as possible.

  In a limited multidrop bus, the termination is typically at the far end of the bus only. The resulting stubs are from the main line to the receiver inputs and these distances should be minimized.

- Segment impedance matching— in a backplane point-to-point bus, the location of the serializer and deserializer is less critical. More important is matching the impedance of all transmission line segments. These impedances should be matched within 10% of the nominal value.

- Controlled impedance differential traces of 100 Ohms are typically recommended for Bus LVDS signals. Edge-coupled microstrip, edge-coupled stripline, or broadside-coupled stripline differential traces may be used. These traces should be closely-coupled (i.e. "s" should be minimized) to ensure coupled noise will appear as common-mode (which is rejected by the receiver). This has the added benefit that closely-coupled lines that are excited with odd-mode transmission tend to radiate less electromagnetic energy.

- Treat the LVDS pair as one signal, avoiding influences that cause imbalances within the pair (see diagram at left). Minimize skew within the pair. Maintain “balance.”

- Leave unused Bus LVDS receiver inputs open (floating) – the internal failsafe in the DS92LV16 will pull the input to a valid state.

- Termination of the Bus LVDS signals is required. The termination resistor value should match the differential impedance of the transmission line. 100-Ohm is a typical value for point-to-point applications. It is better err with too large a termination resistor than too small.

- Isolate TTL/CMOS signals from Bus LVDS signals, placing them at least "3s" or "2w" away—whichever is larger. This will help to prevent them from coupling onto the LVDS lines.

These are just a few common practices that should be followed when designing PCBs for LVDS signaling. General application guidelines are available in the LVDS Owner’s Manual and other documents at www.national.com/lvds.
Cables & Connectors

Cables

The DS92LV16 can be used over a wide variety of balanced cables depending on distance and signal quality requirements. In general, twinax or twisted pair cables are recommended.

- **Typical Connections** can be made using category 5 (CAT5) twisted pair ethernet cable with RJ-45 connectors. See graph at right for typical data rate versus cable distance.

- **Higher Speed Links**: AMP Z-PACK® cables or other twinax cables can be used.

- **Higher Pincount**: SCSI-type cables and connectors or LVDS-type cable assemblies such as the 3M™ MDR and Amphenol SKEW/CLEAR® systems are commonly used.

- **Very Short Distances** (< 0.3 m): flex circuit (following correct PCB layout) or unbalanced ribbon cable may even be used.

If running multiple Bus LVDS pairs in the same cable assembly, use individually shielded pairs to minimize crosstalk between the pairs. At least one ground conductor should be used in the cable (connecting to the DS92LV16 analog grounds (AGNDs)) to provide a known, low impedance return path for common mode currents.

A termination resistor $R_L$, placed as close as possible to the receiver inputs in point-to-point applications, is required. The resistor value should be chosen to match the differential impedance of the cable.

Connectors

Connectors with differential conductors offer the highest performance, but are not necessary in typical, lower speed or short distance applications. For single-ended connectors, keep LVDS pins away from other signals, particularly TTL/CMOS/LVTT/LVC莫斯 signals. The “+” and “-” signals of a pair should be routed on the same row in multi-row connectors to help minimize skew. For high-speed applications (> 800 Mbps) using differential-optimized connectors is recommended.
Power & Ground

General Recommendations

A solid power/ground system is the foundation on which a reliable interconnect system is built. Design circuit board layout and stack-up for the system to provide noise-free power to the device. Good layout practice will separate high frequency and high level inputs and outputs to minimize unwanted stray noise pickup, feedback, and interference. Power system performance may be greatly improved by using thin dielectrics (4 to 10 mils) for power/ground sandwiches. This increases the intrinsic capacitance of the PCB power system, which improves power supply filtering—especially at high frequencies—making the value and placement of external bypass capacitors less critical. External bypass capacitors should include both RF ceramic and tantalum electrolytic types. Use RF capacitors in the range of 0.001 µF to 0.1 µF. Use tantalum capacitors in the range of 2.2 µF to 10 µF. The voltage rating of tantalum capacitors should be at least 3 (5 preferred) times the power supply voltage being used.

It is recommended practice to use two vias at each power/ground pin as well as all RF bypass capacitor terminals. Dual vias reduce the interconnect inductance by up to half, thereby extending the effective range of bypass components. Locate RF capacitors as close as possible to the supply pins and use wide, low impedance traces—not 50-Ohm traces. Surface mount capacitors are recommended due to lower parasitics. When using multiple capacitors per supply pin, locate the smallest value closest to the supply pin. A bulk capacitor is recommended at the point of power entry. This is typically in the range of 50 µF to 100 µF and will smooth low frequency noise.

Some devices have separate power/ground pins for different portions of the circuits to isolate switching noise effects between different blocks. Connecting these to separate power/ground planes on the PCB is typically not required. Pin description tables typically describe which blocks are connected to which power/ground pins. In some cases, an external filter may be used to provide clean power to sensitive circuits such as PLLs.

DS92LV16 Recommendations

General device-specific bypassing recommendations are given below. Actual best practice depends on other board and system level criteria including board density, power rail and power supply type, and the supply needs of other integrated circuits on the board.

PVDD/PGND PLL Supply

The PVDD pins (the DS92LV16 has 2 PVDD pins) supply the PLL circuits. PLLs require a clean supply—less than 100 mV noise peak-to-peak—for the minimization of jitter. PVDD noise in the frequency range 200 kHz to 5 MHz can increase jitter and reduce noise margins. Certain power supplies may have switching frequencies or high harmonic content in this range. If this is the case, filtering of this noise spectrum may be required. A notch filter response is best to provide stable VDD, suppression of the noise band, and good high frequency response (clock fundamental). This may be accomplished with a CRC or CLC pie filter. If employed, a separate pie filter is recommended for each PLL to minimize the voltage drop due to series resistance. Separate board power planes for each PVDD are typically not required.

AVDD/AGND LVDS Supply

The AVDD pins (the DS92LV16 has 4 AVDD pins) supply the LVDS circuits. Due to the nature of the DS92LV16 design, large currents are not drawn through these pins and a 0.1 µF capacitor is sufficient for these pins. If space is available, a 0.01 µF capacitor may be used in parallel with the 0.1 µF capacitor for additional high frequency filtering. Connect the AGND ground to the cable ground to provide a
return path for any common (even) mode currents. Most of the LVDS current is odd-mode and returns within the pair, though a small amount of odd-mode current may be present due to coupled noise and the cable ground should return through a low impedance path to AGND.

**DVDD/DGND Digital Supply**

The DVDD pins supply the digital portion of the device and also the receiver output drivers. The receiver DVDD is more critical than the transmitter DVDD because it must power the receiver outputs during multiple output switching conditions. Four DS92LV16 receiver outputs are powered by each DVDD pin, suggesting that a minimum local bypass capacitance of 28 nF is required. This is calculated by taking 4 times the maximum short circuit current (4 x 85 mA = 340 mA), multiplying by the output rise time (4 ns), and then dividing by the maximum allowed VDD droop (assume 50 mV) and yields 27.2 nF. Rounding up, a standard 0.1 µF is selected for each DVDD pin.

**Power Up Sequencing**

The DS92LV16 does not require a specific power up sequence. Best practice is: power up all VDD pins together, apply clocks (RefCLK & TCLK), and then bring /PWDN powerdown pins high to enable the transmit and/or receive channels. The chip has a power-on reset (POR) circuitry which holds the outputs in TRI-STATE until the supply is above approximately 2.5V. Since all VDD pins (PVDD, AVDD, & DVDD) are related internally, they must be powered up and down together.

---

**Power Dissipation: Transmitter + Receiver**

---

**Tip**

**Comparing Power Consumption**

There is no industry-standard method for specifying power consumption in SerDes datasheets. Power consumption varies significantly with output load, pattern, clock frequency, and the number of channels tested. Even so-called “worst-case” power consumption conditions vary greatly from vendor to vendor. For instance, many vendors do not include the receiver parallel output bus load current.

The DS92LV16 maximum datasheet power consumption is specified at worst case voltage (3.6 V), temperature, and pattern (checkerboard, i.e. alternating LVTTL ones and zeros) with 15 pF load on all CMOS outputs and both transmit & receive channels running at maximum clock frequency (80 MHz).
Clocking

Transmit Clock (TCLK)

The transmit clock (TCLK) rising edge is used by the transmit block to latch in the DIN[0:15] parallel bus and run the transmitter’s PLL. The TCLK input is LVTTL/LVCMOS compatible.

The TCLK clock input tolerates jitter of 80 ps RMS allowing the use of non-telecom/datacom-grade clock sources. The receiver output clock RCLK can also be fed back to TCLK and data retransmitted as an external loopback or repeater, though only two “hops” total are recommended before filtering out accumulated clock jitter. Excessive jitter, especially in the range of 200 kHz - 2 MHz, can appear on the serial outputs reducing link noise margins.

Be careful not to confuse RMS and peak-to-peak jitter. For a typical clock signal with mostly random jitter (i.e. gaussian distribution), the jitter tolerance of 80 ps RMS is by definition approximately 1128 ps peak-to-peak at a 10^-12 bit error rate (BER).

If TCLK is interrupted, the chipset will go through the resynchronization procedure upon reapplication of valid TCLK.

Receiver Reference Clock (RefCLK)

The receiver reference clock is an LVTTL/LVCMOS compatible input and is used by the receiver to establish receiver PLL lock and prevent locking to a false harmonic. Therefore, the RefCLK characteristics are not very critical and the RefCLK frequency need only be within ±5% of the TCLK frequency of the transmitter from which the chip is receiving data. Unless a loopback test is being performed, this RefCLK frequency need not be the same frequency as the chip’s own TCLK signal since the transmit and receive blocks are fully independent, i.e. upstream and downstream data rates are independent.

The relaxed RefCLK specs mean that the RefCLK signal can be generated locally using a common, low cost clock source. In fact, the RefCLK signal could even be removed once the receiver is locked (though this is not recommended).

Receiver Output Clock (RCLK)

The receiver output clock is an LVCMOS output whose rising edge is aligned to the middle of the receiver output data ROUT[0:15]. The subsequent ASIC/FPGA device should latch in ROUT[0:15] data meeting the ASIC’s/FPGA’s input setup and hold times. Output jitter for RCLK is not specified on the datasheet since it depends on the jitter of the incoming data and the TCLK clock source.
Inputs & Outputs

Unused LVTTL Inputs

Unused LVTTL inputs may be left floating or tied high or low. The device datasheet indicates the presence of pull down devices to bias unused pins. These internal impedances tend to be in the 200 kΩ range and may be overridden with lower value pull up resistors if desired. If not using the full 16 bits of the payload, careful attention needs to be taken to avoid disrupting the random lock feature. These unused bits will still be transmitted, so in order for the receiver to maintain random data lock capability, care must be taken not to create a situation where the unused bits cause a repetitive multiple low-high transitions (RMTs). Avoid this by tying bits high at the LSB inputs (starting with DIN0) and bits tied low at the MSB inputs (inputs ending with DIN16).

Floating Bus LVDS Receiver Inputs & Failsafe

In the event that the DS92LV16 receiver is disconnected from the backplane/cable, the internal failsafe circuitry is designed to reject a certain amount of differential noise (about 10mV) from being interpreted as data or clock. This seems like a very small threshold, but balanced, closely-coupled LVDS lines tend to pick up noise as common mode—not differential. The CMOS ROUT[0:15] outputs of the DS92LV16 deserializer will be TRI-STATE when the incoming serial data is removed and the receiver loses lock. Additional failsafe biasing can be implemented externally (see application note AN-1194 and LVDS Owner’s Manual sections 4.6.2-3) at the expense of two additional resistors.

Receiver CMOS Output Drive

The receiver CMOS outputs are specified at ±9 mA. This is typically sufficient to drive 2-3 LVTTL/LVCMOS loads. If more loads will be driven, especially at higher clock speeds, a logic buffer is recommended. Note that depending on actual configuration (number of loads, stub lengths, segment distances, etc.), the receiver output bus may need to be treated as a transmission line and proper LVTTL/LVCMOS termination techniques employed.
Evaluating the DS92LV16

Evaluation Board

The DS92LV16 evaluation kit provides the ability to evaluate the DS92LV16 over AMP Z-Pack cables (1 meter cable included) or any user-supplied interconnect (modified to connect to the boards). The user manual can be downloaded from the web at www.national.com/lvds and the kit itself ordered from authorized distributors as part number BLVDS16EVK subject to availability.

Probing Bus LVDS Signals

LVDS signals are high speed, low swing signals. Improper probing can result in deceiving results since the probe and/or scope can filter high speed components of the signal. Using a ≥1 GHz bandwidth scope (such as the Agilent 86100 or Tektronix 694C) and a high speed differential probe (such as the Tektronix P6247/8 or P6330) is highly recommended. LVDS drivers are not compatible with 50-Ohm probes.

PRBS pattern at serializer output. Note the embedded low/high clock 0/1 bits.

SYNC pattern at serializer output.
Loopback Testing

The line and local loopback modes allow the designer to isolate and test selected portions of the system.

**Local Loopback**

Asserting the LOCAL_LE pin high connects the parallel LV TTL data bus DIN[0:15] internally to the receiver output ROUT[0:15]. This mode includes all the functional blocks of the SerDes pair except the Bus LVDS input and output structures (the transmitter Bus LVDS outputs are in TRI-STATE). Switching the DS92LV16 to local loopback mode, therefore, means the receiver will relock to the loopback data and RefCLK must be within ±5% of the local TCLK frequency. The local loopback mode allows the local card to verify it is sending, receiving, and processing data properly.

**Line Loopback**

The DS92LV16 will enter the line loopback mode when the LINE_LE pin is brought high. This connects the Bus LVDS transmitter output (DO) pins internally to the receiver input (RIN) pins and to the parallel LV TTL data bus ROUT[0:15]. This loopback test mode includes the serializer/deserializer blocks. The line loopback mode allows the system to verify that the board-to-board links are operating properly.

Due to the relaxed clocking requirements of the DS92LV16, external line loopback within an FPGA or ASIC can also easily be performed to test portions of the system logic in addition to the DS92LV16 and interconnect.
Lock to Random Data vs. SYNC Patterns

SYNC Patterns

SYNC patterns, “H11111100000000L” where “H” is the clock 1 bit (high) and “L” is the clock 0 bit (low), are sent automatically by the transmitter when the SYNC pin is held high. The receiver will lock to this pattern within a guaranteed time (see $t_{DSR}$ specified in the datasheet). When the deserializer’s /LOCK pin goes high, the receiver has locked to the incoming data stream and valid data appears at the receiver outputs.

Lock to Random Data

The receiver will also lock to random data without external system intervention, providing a powerful “plug & go” system capability not provided by most SerDes chipsets. In order to achieve this, the receiver looks for a consistent low-high transition caused by the clock 0,1 bits. If there are two data bits consistently “stuck” low-high over multiple clock cycles (known as a repetitive multiple transition or RMT), the receiver will not lock until these bits change and the receiver recognizes the unique embedded clock low-to-high transition.

Sending SYNC Patterns versus Lock to Random Data

Sending SYNC patterns has the advantage that the receiver lock time is guaranteed to be less than $t_{DSR \text{ max}}$. This can be useful in some systems and the sending of SYNC patterns can be achieved by controlling the SYNC pin through system logic or by feeding back the /LOCK pin to the SYNC pin.

The receiver will lock to random data without system intervention, though the lock time will depend on the data pattern. This feature is useful in systems in which there is no quick or easy feedback path from receiver to transmitter or in systems which can’t afford to interrupt data flow by sending special training patterns.

Both lock modes, sending SYNC patterns and the locking to random data, are viable synchronization methods. Either may be employed and in fact, some systems may choose to employ both methods.

Once Lock is Achieved

After the receiver is locked, it will stay locked regardless of data pattern: fixed (with or without RMTs), random, periodic, SYNC patterns, or a mix of these patterns. The receiver loses lock and enters the “acquire lock” state only after it detects two consecutive clock 0,1 bit errors. Once locked, the data between the clock bits do not affect the receiver’s PLL.
Interconnect Jitter Budget

Interconnect jitter budget is the amount of interconnect loading that can occur on the link before bit errors occur and is simply the ideal receiver noise margin specification. The latest DS92LV16 datasheets specify both left and right T_{RNMI} specifying how much jitter the receiver can tolerate on either side of the ideal bit edge before bit errors occur. The T_{RNMI} specifications also allow the construction of an eye mask to validate the application’s signal quality. Jitter sources include:

- External Noise: This includes excessive power supply noise, cross talk, etc.
- Interconnect Effects: Inter-symbol interference (ISI), attenuation, etc.
- Clock Jitter: excessive jitter on the serializer transmit clock TCLK.

Validating Signal Quality

In conjunction with bit error rate test (BERT) measurements, eye pattern measurements are a good way to validate the robustness of a high speed link. While BER tests generally produce a pass/fail result, viewing the eye pattern at the receiver inputs gives a more qualitative indication of how much margin a given link has. The amount of “eye opening” around the receiver input jitter mask is a qualitative measure of the link’s noise margin.

The receiver input jitter mask is constructed in the following steps:

1) Make sure the link is operating and sending the desired pattern (normally a PRBS pattern).

<table>
<thead>
<tr>
<th>MHz</th>
<th>ns</th>
<th>MHz</th>
<th>ns</th>
</tr>
</thead>
<tbody>
<tr>
<td>30</td>
<td>1.852</td>
<td>50</td>
<td>1.111</td>
</tr>
<tr>
<td>30.72</td>
<td>1.808</td>
<td>52</td>
<td>1.068</td>
</tr>
<tr>
<td>33</td>
<td>1.684</td>
<td>61.44</td>
<td>0.904</td>
</tr>
<tr>
<td>35</td>
<td>1.587</td>
<td>62.5</td>
<td>0.889</td>
</tr>
<tr>
<td>38.8</td>
<td>1.432</td>
<td>66</td>
<td>0.842</td>
</tr>
<tr>
<td>39.44</td>
<td>1.409</td>
<td>78.88</td>
<td>0.704</td>
</tr>
<tr>
<td>40</td>
<td>1.389</td>
<td>80</td>
<td>0.694</td>
</tr>
</tbody>
</table>

Ideal Bit Width = 1/TCLK frequency / 10

Important: Make calculations to the nearest picosecond.
2) Capture the entire eye pattern at the receiver inputs using a high bandwidth oscilloscope in variable persistence mode with a high speed (> 1 GHz), high impedance (> 100 kΩ) differential probe. The TCLK signal should be used as the trigger.

**Eye Pattern**

*Full eye pattern captured by the scope set to variable persistence mode.*

3) Use the vertical cursor function of the scope to place a vertical cursor over the average 0V differential crossing point of the clock-0-bit/clock-1-bit low-to-high transition. This cursor position is now the ideal time point to which all other positions will be referenced.

**Ideal Waveform**

*Ideal bit edge positions are always multiples of T/18 away from the ideal clock0-clock1 low to high transition.*

**Align ideal waveform to eye pattern here**

*The receiver jitter margin for any bit on the eye pattern can be calculated based on its ideal bit edge positions.*

*Note: These eye patterns are computer-generated for clarity.*
Interconnect Jitter Budget (continued)

4) Select the bit “eye” pattern in which to place the receiver input jitter mask. The worst case bit, i.e. the bit with the most “closed” eye, is recommended. The ideal crossing points on either side of the n^th data bit will be n*T/18 and (n+1)*T/18 away from the ideal stop-start crossing point set in step 3, where T is period of the TCLK frequency. (16 data bits plus 2 clock bits = 18 bits.)

5) Calculate the ideal bit edges, being careful to avoid rounding errors, and place a cursor at both ideal bit edges of the selected bit.

6) Add tRNMI-left to the ideal left bit edge and tRNMI-right to the right ideal edge to get the positions of the receiver input jitter mask.

7) The height of the jitter mask is the receiver’s differential input threshold VT_H - VT_L. This is typically ± 50 mV, though the datasheet value of ± 100 mV can be used if a more conservative estimate is desired.

8) The receiver input jitter mask should now look like a box inside the “eye” of the bit. The “white area” (shown in green in the diagram at right) around the box is the relative noise margin of the link. As long as the captured eye opening stays out of this noise margin “box,” the chipset should operate error-free.

Alternative Jitter Measurements

The tRNMI-left/right specs can also be used to get a quantitative estimate of remaining jitter margin. The quantity (tRNMI - jitter)/tRNMI of the worst case side (see diagram at right) is the percentage jitter margin left before bit errors are expected to occur.

The total amount of jitter budget available for the interconnect (i.e. how much jitter budget is allowed for the cable or backplane) is calculated similarly by subtracting maximum transmitter deterministic jitter tDJIT from receiver ideal noise margin tRNMI:

Jitter budget left side: tRNMI - tDJIT (max)
Jitter budget right side: tRNMI - tDJIT (min) (tDJIT min is a negative number)

Note: These eye patterns are computer-generated for clarity.
Troubleshooting

The DS92LV16 is a robust, easy-to-use SerDes and application issues should be rare. If application problems do occur, the causes can normally be traced to a few simple, easy-to-check areas (listed in order of relevance):

- **Power Supply Noise**: Excessive supply noise, especially on the PLL supply (PVCC), can add jitter to the transmitter serial output and affect the receiver data sampling. Keep supply noise under 100 mV peak-to-peak on the PVCC pins.

- **Transmit Clock**: Minimize excessive cycle-to-cycle jitter on the transmit clock TCLK in the range of 200 kHz - 2 MHz which can add jitter to the transmitter serial output.

- **Serial Bus**: Should follow LVDS PCB layout and backplane recommendations, using proper termination, avoiding long stubs, and assuring the termination resistor is close to the receiver input.

- **Parallel Bus**: The parallel LV TTL signals should not violate any setup and hold times and should be free from excessive overshoot/undershoot.
Additional Technical Resources

National Semiconductor LVDS Feature Web Site

www.national.com/lvds is a one-stop-shop for device information and technical information such as application notes, white papers, the LVDS Owner’s Manual, evaluation board documentation, IBIS models, frequently-asked-questions, online seminar materials, and much more.

LVDS Owner’s Manual

The LVDS Owner’s Manual teaches what LVDS is, how it works, what its advantages are, how to design with it. It should be part of every high speed interconnect designer’s library. The LVDS Owner’s Manual can be downloaded from the web at www.national.com/lvds or ordered from one of National’s sales representatives.

RAPIDESIGNER® Slide Rule

National Semiconductor’s Transmission Line RAPIDESIGNER Slide Rule makes PCB stripline and microstrip transmission line calculations quick and easy. The slide rule is available in both metric and English unit versions. Instructions and equations are given in application note AN-905.

Contact Information

See back cover for contact information or visit www.national.com/contacts.
For More Information

Web
• Visit our web site at www.national.com/lvds for more technical information. For sample orders, please click on the product name under “Product Folder.”

Email/Phone/Fax

Americas
Email: support@ns.com
Phone: 1-800-272-9959
Fax: 1-800-737-7018

Europe
Email: europe.support@ns.com
Phone: Deutsch +49 (0) 69 9508 6208
English +44 (0) 870 24 0 2171
Français +33 (0) 1 41 91 87 90
Fax: +49 (0) 180-530 85 86

Asia Pacific
Email: ap.support@ns.com
Phone: 65-2544 466
Fax: 65-2504 466

Japan
Email: nsj.crc@jksmtip.nsc.com
Phone: 81-3-5639-7560
Fax: 81-3-5639-7507

Nearest Distributors
• To find your nearest distributors, please visit www.national.com/contacts
IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal and regulatory requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any damages arising out of the use of TI products in such applications.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

<table>
<thead>
<tr>
<th>Products</th>
<th>Applications</th>
</tr>
</thead>
<tbody>
<tr>
<td>Audio</td>
<td>Communications and Telecom</td>
</tr>
<tr>
<td>Amplifiers</td>
<td>Computers and Peripherals</td>
</tr>
<tr>
<td>Data Converters</td>
<td>Consumer Electronics</td>
</tr>
<tr>
<td>DLP® Products</td>
<td>Energy and Lighting</td>
</tr>
<tr>
<td>DSP</td>
<td>Industrial</td>
</tr>
<tr>
<td>Clocks and Timers</td>
<td>Medical</td>
</tr>
<tr>
<td>Interface</td>
<td>Security</td>
</tr>
<tr>
<td>Logic</td>
<td>Space, Avionics and Defense</td>
</tr>
<tr>
<td>Power Mgmt</td>
<td>Transportation and Automotive</td>
</tr>
<tr>
<td>Microcontrollers</td>
<td>Video and Imaging</td>
</tr>
<tr>
<td>RFID</td>
<td></td>
</tr>
<tr>
<td>OMAP Mobile Processors</td>
<td></td>
</tr>
<tr>
<td>Wireless Connectivity</td>
<td></td>
</tr>
</tbody>
</table>

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2011, Texas Instruments Incorporated